PROCEEDINGS OF SPIE

Infrared Sensors, Devices, and Applications XIV

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20–21 August 2024 San Diego, California, United States

Sponsored and Published by SPIE

Volume 13145

The papers in this volume were part of the technical conference cited on the cover and title page. Papers were selected and subject to review by the editors and conference program committee. Some conference presentations may not be available for publication. Additional papers and presentation recordings may be available online in the SPIE Digital Library at SPIEDigitalLibrary.org.

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Please use the following format to cite material from these proceedings: Author(s), "Title of Paper," in *Infrared Sensors, Devices, and Applications XIV*, edited by Priyalal Wijewarnasuriya, Arvind I. D'Souza, Ashok K. Sood, Proc. of SPIE 13145, Seven-digit Article CID Number (DD/MM/YYYY); (DOI URL).

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781510679504

ISBN: 9781510679511 (electronic)

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA Telephone +1 360 676 3290 (Pacific Time)

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